



General Description

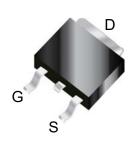
These N-Channel enhancement mode power field effect transistors are using trench MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

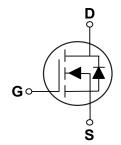
BV _{DSS}	R _{DS(ON)}	Ι _D
80 V	3.4 mΩ	165 A

Features

- $R_{DS(ON)} \leq 3.4 \text{m}\Omega @V_{GS} = \overline{10V}$
- · Fast Switching
- · Green Device Available

TO-263 Pin Configuration





Applications

- Networking
- · Load Switch
- LED Applications
- Quick Charger

Absolute Maximum Ratings T_C=25°C unless otherwise noted Symbol **Parameter** Rating Units V_{DS} Drain-Source Voltage 80 V_{GS} ٧ Gate-Source Voltage ±20 165 I_D Drain Current – Continuous (T_C=25°C) Α Drain Current - Pulsed (NOTE 1) I_{DM} 660 EAS Single Pulse Avalanche Energy (NOTE 2) 520 mJ P_D Power Dissipation (T_C=25°C) 240 W T_J Operating Junction Temperature Range -55 to 150 °C Storage Temperature Range -55 to 150 T_{STG} ٥С Marking Code NK3P4

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	62	°C/W		
$R_{\theta JC}$	Thermal Resistance Junction to Case	0.52	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	80			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			3.4	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	2		4	V
gfs	Forward Transconductance	V _{DS} =10V , I _D =3A		13		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			68		
Q_gs	Gate-Source Charge	V_{DS} =40V , V_{GS} =10V , I_{D} =80A		19		nC
Q_{gd}	Gate-Drain Charge			20		
$T_{d(on)}$	Turn-On Delay Time			30		
T_r	Rise Time	V_{DD} =40V , R_G =6 Ω , I_D =80A ,		25	-	nS
$T_{d(off)}$	Turn-Off Delay Time	V _{GS} =10V		45		110
T_f	Fall Time			25		
C_{iss}	Input Capacitance	V _{DS} =40V , V _{GS} =0V , F=1MHz		4600		
C_{oss}	Output Capacitance			990		pF
C_{rss}	Reverse Transfer Capacitance			16		
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , F=1MHz		1.8		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Body Diode Current	V _G =V _D =0V , Force Current			165	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1	V
t _{rr}	Reverse Recovery Time	V _R =50V , I _S =10A ,		70		nS
Q_{rr}	Reverse Recovery Charge	dI _F /dt=100A/us		160		nC

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =50V, L=0.1mH, I_{AS} =102A, V_{GS} =10V.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- ${\bf 4.} \ Essentially \ independent \ of \ operating \ temperature.$





Characteristics Curves

FIG. 1- I_D vs. T_C 175 150 125 € 100 50 25 ⊥ 75 T_C 0∟ 25 50 100 125 150

(°C)

FIG. 2- Normalized $R_{DS(ON)}$ vs. T_J

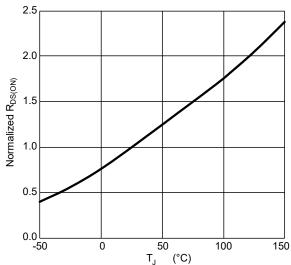


FIG. 3- Normalized $V_{\text{GS(th)}}$ vs. T_{J}

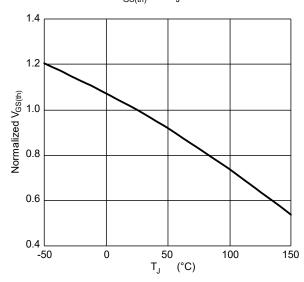


FIG. 4-Gate Charge Characteristics

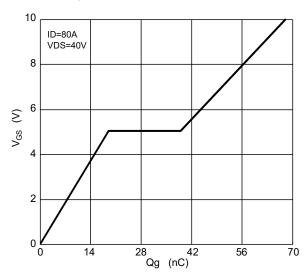


FIG. 5- Normalized Transient Impedance

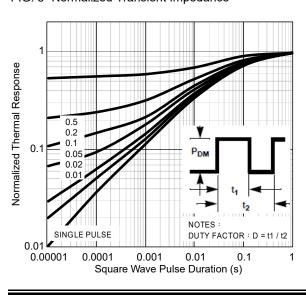
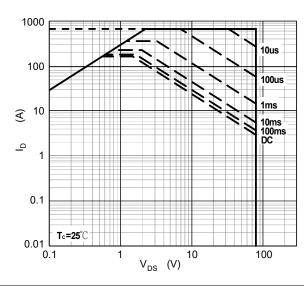


FIG. 6-Safe Operation Area







Characteristics Curves

FIG. 7- Switching Time Waveform

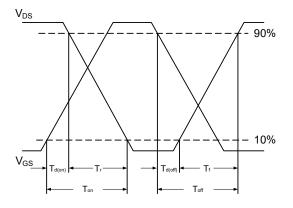
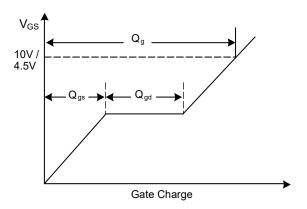
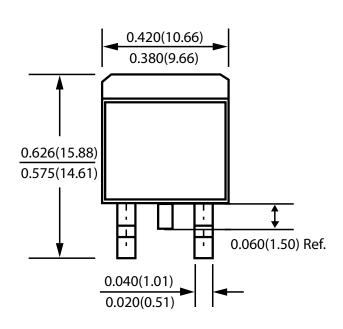
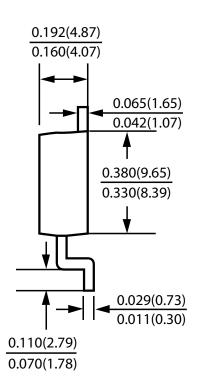


FIG. 8- Gate Charge Waveform



Package Outline Dimensions





TO-263Dimensions in inches and (millimeters)





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